SN54HC138, SN74HC138 3-LINE TO 8-LINE DECODERS/DEMULTIPLEXERS

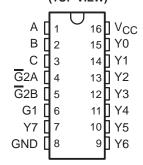
SCLS107E - DECEMBER 1982 - REVISED SEPTEMBER 2003

- Targeted Specifically for High-Speed Memory Decoders and Data-Transmission Systems
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 15 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Incorporate Three Enable Inputs to Simplify Cascading and/or Data Reception

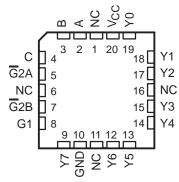
description/ordering information

The 'HC138 devices are designed to be used in high-performance memory-decoding or datarouting applications requiring very short propagation delay times. In high-performance memory systems, these decoders can be used to minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay times of these decoders and the enable time of the memory are usually less than the typical access time of the memory. This means that the effective system delay introduced by the decoders is negligible.

SN54HC138 . . . J OR W PACKAGE SN74HC138 . . . D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



SN54HC138 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

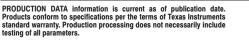
ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – N	Tube of 25	SN74HC138N	SN74HC138N	
		Tube of 40	SN74HC138D		
	SOIC - D	Reel of 2500	SN74HC138DR	HC138	
		Reel of 250	SN74HC138DT		
-40°C to 85°C	SOP - NS	Reel of 2000	SN74HC138NSR	HC138	
	SSOP – DB	Reel of 2000	SN74HC138DBR	HC138	
		Tube of 90	SN74HC138PW		
	TSSOP - PW	Reel of 2000	SN74HC138PWR	HC138	
		Reel of 250	SN74HC138PWT		
	CDIP – J	Tube of 25	SNJ54HC138J	SNJ54HC138J	
-55°C to 125°C	CFP – W	Tube of 150	SNJ54HC138W	SNJ54HC138W	
	LCCC – FK	Tube of 55	SNJ54HC138FK	SNJ54HC138FK	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SN54HC138, SN74HC138 3-LINE TO 8-LINE DECODERS/DEMULTIPLEXERS

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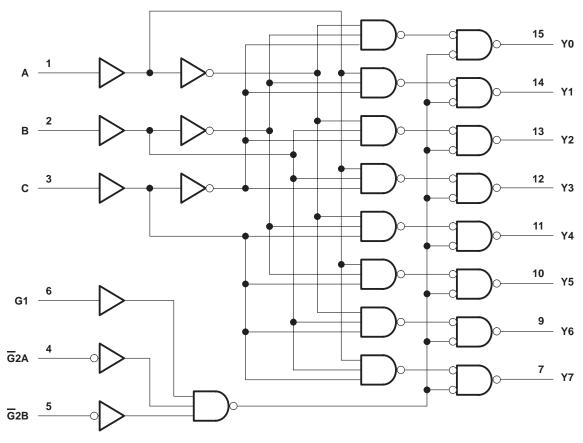
description/ordering information (continued)

The conditions at the binary-select inputs at the three enable inputs select one of eight output lines. Two active-low and one active-high enable inputs reduce the need for external gates or inverters when expanding. A 24-line decoder can be implemented without external inverters, and a 32-line decoder requires only one inverter. An enable input can be used as a data input for demultiplexing applications.

FUNCTION TABLE

		INP							OUT	PUTS			
	ENABLE			SELEC1	•				0011	0.0			
G1	G2A	G2B	С	В	Α	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
Х	Н	Χ	Х	Χ	Χ	Н	Н	Н	Н	Н	Н	Н	Н
Х	X	Н	Χ	X	X	Н	Н	Н	Н	Н	Н	Н	Н
L	X	X	Χ	Χ	Χ	Н	Н	Н	Н	Н	Н	Н	Н
Н	L	L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н
Н	L	L	L	L	Н	Н	L	Н	Н	Н	Н	Н	Н
Н	L	L	L	Н	L	Н	Н	L	Н	Н	Н	Н	Н
Н	L	L	L	Н	Н	Н	Н	Н	L	Н	Н	Н	Н
Н	L	L	Н	L	L	Н	Н	Н	Н	L	Н	Н	Н
Н	L	L	Н	L	Н	Н	Н	Н	Н	Н	L	Н	Н
Н	L	L	Н	Н	L	Н	Н	Н	Н	Н	Н	L	Н
Н	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L

logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see	ee Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CO}$		
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$		±25 mA
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ_{JA} (see Note 2)	: D package	73°C/W
•••	DB package	82°C/W
	N package	67°C/W
	NS package	64°C/W
	PW package	108°C/W
Storage temperature range, T _{Stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



SN54HC138, SN74HC138 3-LINE TO 8-LINE DECODERS/DEMULTIPLEXERS

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recommended operating conditions (see Note 3)

			SN	SN54HC138		SI	174HC13	8	UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNII	
Vcc	Supply voltage		2	5	6	2	5	6	V	
		V _{CC} = 2 V	1.5			1.5				
ViH	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V	
		V _{CC} = 6 V	4.2			4.2				
		V _{CC} = 2 V			0.5			0.5		
٧ _{IL}	Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V	
		VCC = 6 V			1.8			1.8		
٧ı	Input voltage		0		VCC	0		VCC	V	
٧o	Output voltage		0		Vcc	0		VCC	V	
		V _{CC} = 2 V			1000			1000		
Δt/Δν	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns	
		VCC = 6 V			400			400		
TA	Operating free-air temperature	•	-55		125	-40		85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST SOMBITIONS		VCC	Т	A = 25°C	;	SN54H	C138	SN74HC138		LINUT
PARAMETER	TEST CC	TEST CONDITIONS		MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
∨он	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
	V_{OL} $V_{I} = V_{IH}$ or V_{IL}	I _{OL} = 20 μA	2 V		0.002	0.1		0.1		0.1	
			4.5 V		0.001	0.1		0.1		0.1	
VoL			6 V		0.001	0.1		0.1		0.1	V
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	.,	T	ղ = 25°C	;	SN54H	IC138	SN74H	C138	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		67	180		270		225	
	A, B, or C	Any Y	4.5 V		18	36		54		45	
			6 V		15	31		46		38	
^t pd	Enable	Any Y	2 V		66	155		235		195	ns
			4.5 V		18	31		47		39	
			6 V		15	26		40		33	
			2 V		38	75		110		95	
t _t		Any	4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

operating characteristics, T_A = 25°C

		PARAMETER	TEST CONDITIONS	TYP	UNIT
Г	C _{pd}	Power dissipation capacitance	No load	85	pF

PARAMETER MEASUREMENT INFORMATION **From Output** Test **VCC** Input 50% 50% **Under Test Point** 0 V $C_L = 50 pF$ **tPHL** tPLH -(see Note A) ۷он In-Phase 90% 50% 10% -Output 10% V_{OL} LOAD CIRCUIT - tPHL VCC VOH Input 50% 90% Out-of-Phase 10% Output 10% 10% - Vol **VOLTAGE WAVEFORMS VOLTAGE WAVEFORM INPUT RISE AND FALL TIMES** PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

- NOTES: A. C_L includes probe and test-fixture capacitance.
 - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50~\Omega$, $t_f = 6$ ns, $t_f = 6$ ns.
 - C. The outputs are measured one at a time with one input transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 1. Load Circuit and Voltage Waveforms







i.com 10-May-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-8406201VEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
5962-8406201VFA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
84062012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
8406201EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
8406201FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/65802B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/65802BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/65802BFA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SN54HC138J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN74HC138D	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC138DBR	ACTIVE	SSOP	DB	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC138DR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC138DT	ACTIVE	SOIC	D	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC138N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC138N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74HC138NSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC138NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC138PW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC138PWLE	OBSOLETE	TSSOP	PW	16		TBD	Call TI	Call TI
SN74HC138PWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC138PWT	ACTIVE	TSSOP	PW	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SNJ54HC138FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54HC138J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54HC138W	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

10-May-2005

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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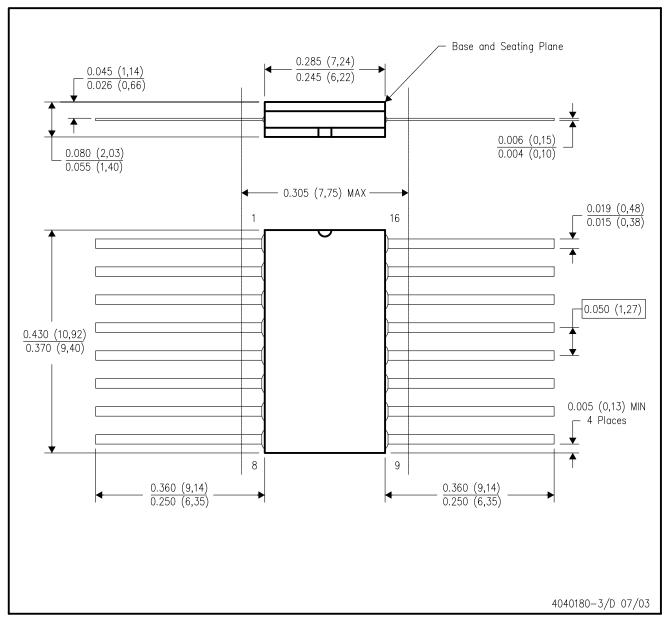
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



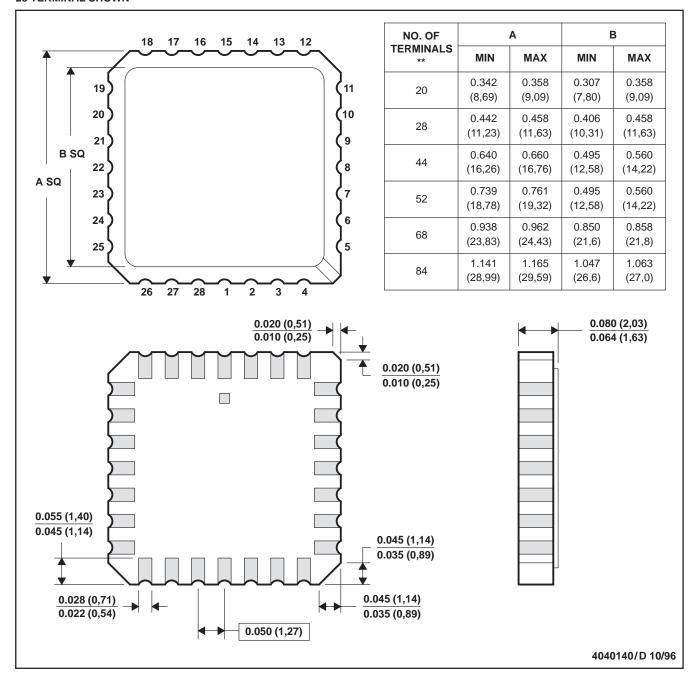
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

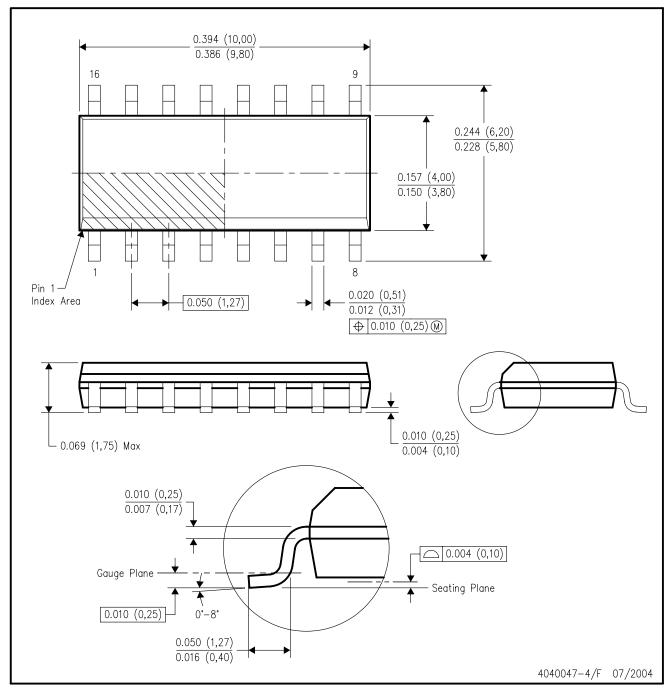


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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